L Number	Hits	Search Text	DB	Time stamp
9	49	((Mask or photoresist or nonwettable) with offset) and opening$1 and (@ad<19991110) and (ball or bump) and (chip or die or microelectronic or device)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:08
10	417333	(Mask or photoresist or nonwettable) ((pad or land) with offset) and opening$1 and (@ad<19991110) and (ball or bump) and (chip or die or microelectronic or device)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:08
11	49	(Mask or photoresist or nonwettable) and ((pad or land) with offset) and opening$1 and (@ad<19991110) and (ball or bump) and (chip or die or microelectronic or device)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:08
12	45	((Mask or photoresist or nonwettable) and ((pad or land) with offset) and opening$1 and (@ad<19991110) and (ball or bump) and (chip or die or microelectronic or device)) not (((Mask or photoresist or nonwettable) with offset) and opening$1 and (@ad<19991110) and (ball or bump) and (chip or die or microelectronic or device))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:16
13	1	("5517756").PN.	USPAT	2004/10/27 13:16
14	820	257/778.ccls. and (@ad<19991110) and solder	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:22
-	0	("2004099936").PN.	USPAT; US-PGPUB	2004/10/26 14:12
-	1	("20040099936").PN.	USPAT; US-PGPUB	2004/10/26 14:21
-	2472	(chip or die or chips or dies) and (Mask with pad$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 14:24
-	1	("6118182").PN.	USPAT	2004/10/26 14:22
-	710	((chip or die or chips or dies) and (Mask with pad$1) and (@ad<19991110)) and (Mask with opening$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:16
-	280	(((chip or die or chips or dies) and (Mask with pad$1) and (@ad<19991110)) and (Mask with opening$1)) and (ball or balls or bump)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 14:26
-	37	5523920.URPN.	USPAT	2004/10/26 14:47
-	1	("6441316").PN.	USPAT	2004/10/26 15:02
-	710	((chip or die or chips or dies) and (Mask with pad$1) and (@ad<19991110)) and (Mask with opening$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:41
-	68	257/778.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/27 13:21
-	18	257/777.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:28
-	69	257/737.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:32

-	17	257/459.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:33
-	76	438/612.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:37
-	60	438/613.ccls. and (Mask with opening$1) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:40
-	1908	(chip or die chips or dies) and (Mask with solder) and (@ad<19991110)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:41
-	956	((chip or die chips or dies) and (Mask with solder) and (@ad<19991110)) and opening$1	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/10/26 15:43